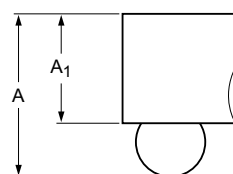
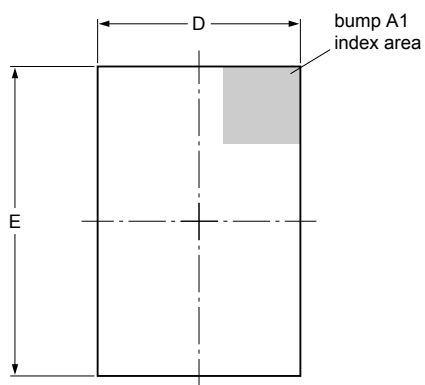
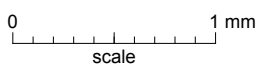
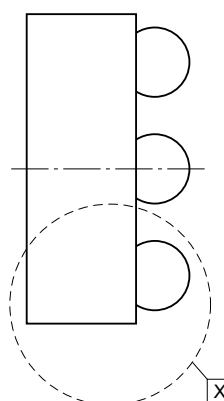
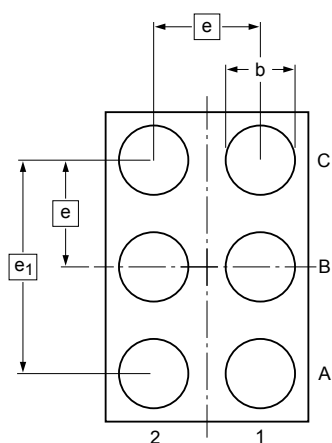


WLCSP6: wafer level chip-size package; 6 bumps (2 x 3)

IP3319CX6




detail X



Dimensions (mm are the original dimensions)

Unit	A	A ₁	b	D	E	e	e ₁
max	0.60	0.38	0.31	1.00	1.39	0.42	0.84
nom	0.57	0.37	0.26	0.95	1.34	0.40	0.80
min	0.54	0.36	0.21	0.90	1.29	0.38	0.76

ip3319cx6_po

Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
IP3319CX6						13-06-07 13-06-10